



Material Content Data Sheet



Sales Product Name		BFP 460 H6327		Issued		20. July 2018		
MA#		MA000801724						
Package		PG-SOT343-4-1		Weight*		6.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.03		268	
	non noble metal	tin	7440-31-5	0.000	0.01		69	
	inorganic material	silicon	7440-21-3	0.013	0.20	0.24	1984	2321
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		499	
	non noble metal	chromium	7440-47-3	0.010	0.15		1497	
	non noble metal	copper	7440-50-8	3.347	49.68	49.89	496815	498911
wire	noble metal	gold	7440-57-5	0.013	0.19	0.19	1910	1910
encapsulation	organic material	carbon black	1333-86-4	0.031	0.46		4574	
	plastics	epoxy resin	-	0.663	9.83		98349	
	inorganic material	silicondioxide	60676-86-0	2.389	35.45	45.74	354513	457436
leadfinish	non noble metal	tin	7440-31-5	0.202	2.99	2.99	29941	29941
plating	noble metal	silver	7440-22-4	0.064	0.95	0.95	9481	9481
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com